

DATA SHEET

BT137B series Triacs

Product specification

June 2001



Triacs

BT137B series

GENERAL DESCRIPTION

Passivated triacs in a plastic envelope suitable for surface mounting, intended for use in applications requiring high bidirectional transient and blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

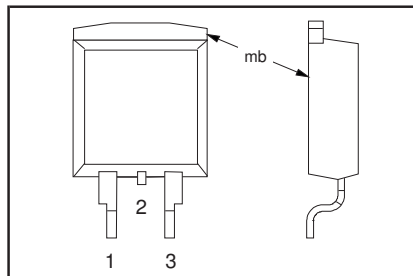
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
V_{DRM}	Repetitive peak off-state voltages	600 600F 600G 600	800 800F 800G 800	V
$I_{T(RMS)}$	RMS on-state current	8	8	A
I_{TSM}	Non-repetitive peak on-state current	65	65	A

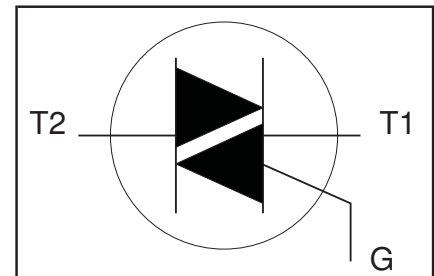
PINNING - SOT404

PIN	DESCRIPTION
1	main terminal 1
2	main terminal 2
3	gate
mb	main terminal 2

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT
				-600 600 ¹	-800 800	
V_{DRM}	Repetitive peak off-state voltages		-	-600 600 ¹	-800 800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 102\text{ }^{\circ}\text{C}$	-	8		A
I_{TSM}	Non-repetitive peak on-state current	full sine wave; $T_j = 25\text{ }^{\circ}\text{C}$ prior to surge	-	65		A
I^2t	I^2t for fusing	$t = 20\text{ ms}$	-	71		A
dl_T/dt	Repetitive rate of rise of on-state current after triggering	$t = 16.7\text{ ms}$	-	21		A ² s
		$t = 10\text{ ms}$	-	50		A/μs
		$I_{TM} = 12\text{ A}; I_G = 0.2\text{ A}; dl_G/dt = 0.2\text{ A}/\mu\text{s}$	-	50		A/μs
		T2+ G+	-	50		A/μs
		T2+ G-	-	50		A/μs
		T2- G-	-	10		A/μs
		T2- G+	-	2		A
I_{GM}	Peak gate current		-	5		V
V_{GM}	Peak gate voltage		-	5		W
P_{GM}	Peak gate power		-	0.5		W
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	150		°C
T_{stg}	Storage temperature		-40	125		°C
T_j	Operating junction temperature		-			°C

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 6 A/μs.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base	full cycle	-	-	2.0	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	half cycle minimum footprint, FR4 board	-	-	2.4	K/W
			-	55	-	K/W

STATIC CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT		
I_{GT}	Gate trigger current	BT137B- $V_D = 12\text{ V}; I_T = 0.1\text{ A}$		F ...G		
		T2+ G+	-	5	35	25	50	mA
		T2+ G-	-	8	35	25	50	mA
		T2- G-	-	11	35	25	50	mA
I_L	Latching current	$V_D = 12\text{ V}; I_{GT} = 0.1\text{ A}$						
		T2- G+	-	30	70	70	100	mA
		T2+ G+	-	7	30	30	45	mA
		T2+ G-	-	16	45	45	60	mA
I_H	Holding current	$V_D = 12\text{ V}; I_{GT} = 0.1\text{ A}$						
		T2- G-	-	5	30	30	45	mA
		T2- G+	-	7	45	45	60	mA
			-	5	20	20	40	mA
V_T	On-state voltage	$I_T = 10\text{ A}$	-	1.3	1.65		V	
V_{GT}	Gate trigger voltage	$V_D = 12\text{ V}; I_T = 0.1\text{ A}$	-	0.7	1.5		V	
		$V_D = 400\text{ V}; I_T = 0.1\text{ A}; T_j = 125\text{ °C}$	0.25	0.4	-		V	
I_D	Off-state leakage current	$V_D = V_{DRM(max)}; T_j = 125\text{ °C}$	-	0.1	0.5		mA	

DYNAMIC CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT	
dV_D/dt	Critical rate of rise of off-state voltage	BT137B- $V_{DM} = 67\% V_{DRM(max)}; T_j = 125\text{ °C};$ exponential waveform; gate open circuit	100	50	200	250	V/ μ s
dV_{com}/dt	Critical rate of change of commutating voltage	$V_{DM} = 400\text{ V}; T_j = 95\text{ °C}; I_{T(RMS)} = 8\text{ A}; dl_{com}/dt = 3.6\text{ A/ms};$ gate open circuit	-	-	10	20	V/ μ s
t_{gt}	Gate controlled turn-on time	$I_{TM} = 12\text{ A}; V_D = V_{DRM(max)}; I_G = 0.1\text{ A}; dl_G/dt = 5\text{ A}/\mu$ s	-	-	-	2	μ s

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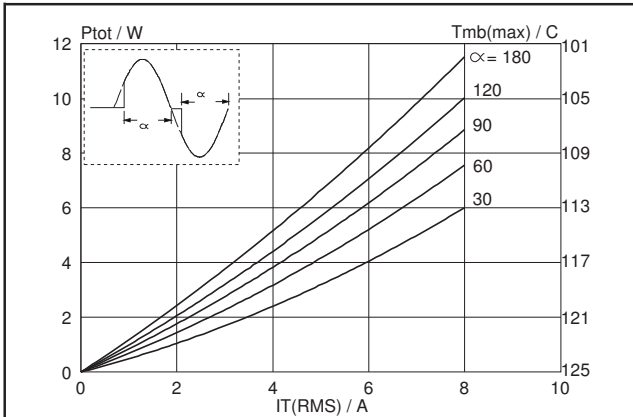


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where $\alpha =$ conduction angle.

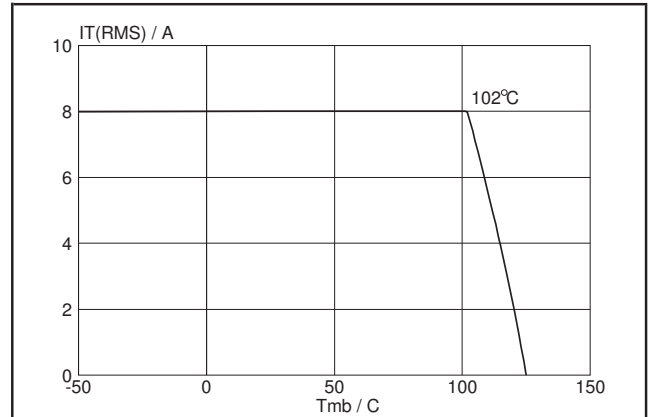


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

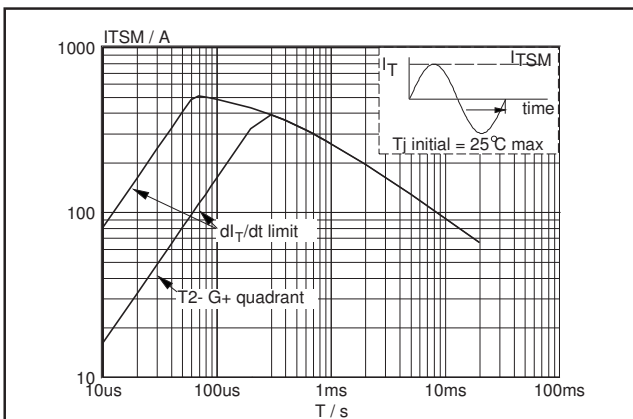


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \leq 20$ ms.

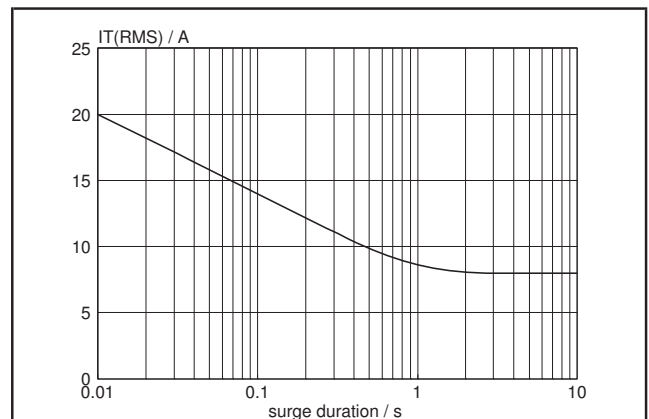


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, $f = 50$ Hz; $T_{mb} \leq 102^\circ$ C.

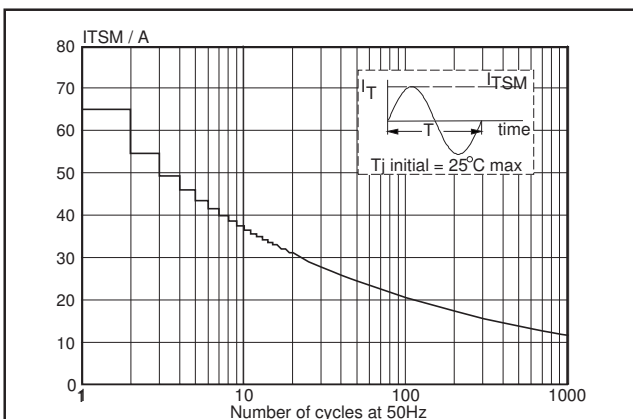


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, $f = 50$ Hz.

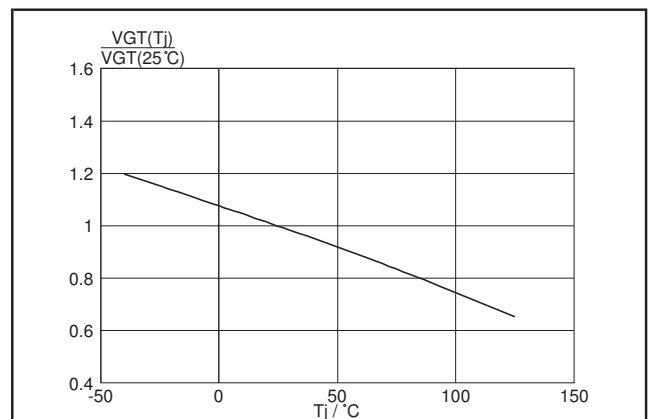
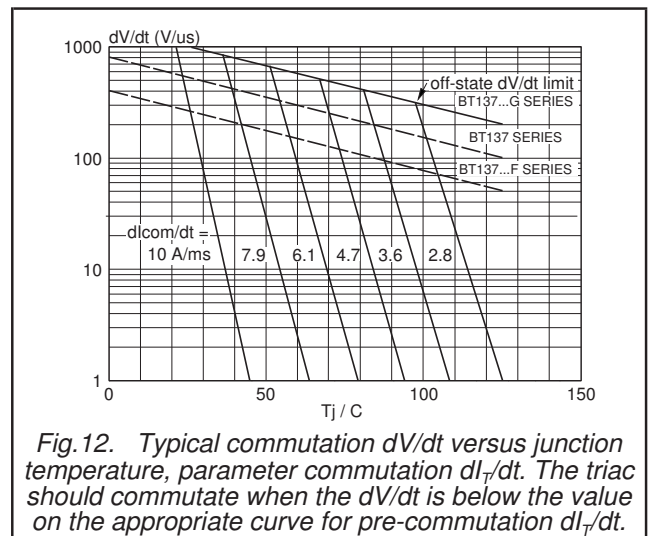
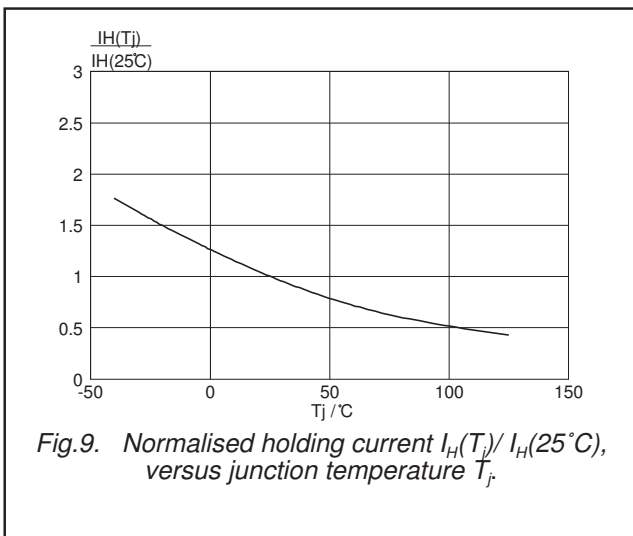
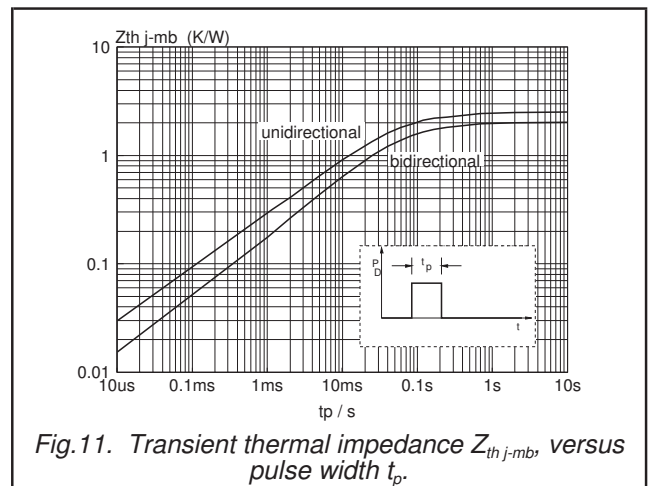
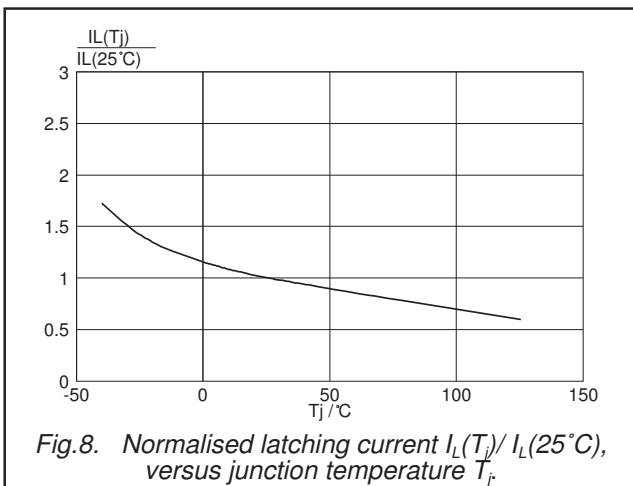
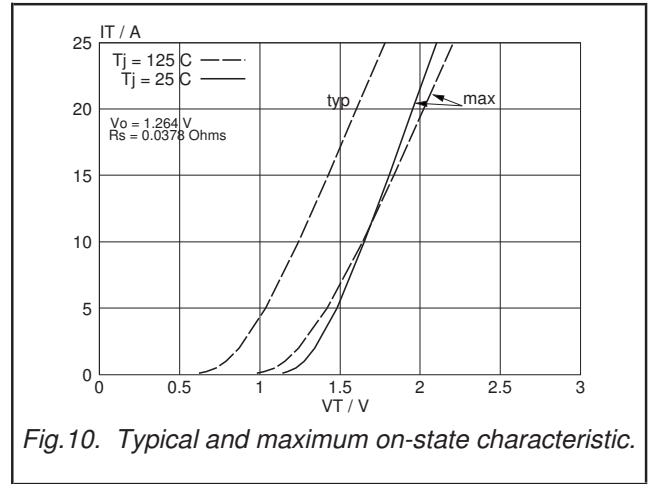
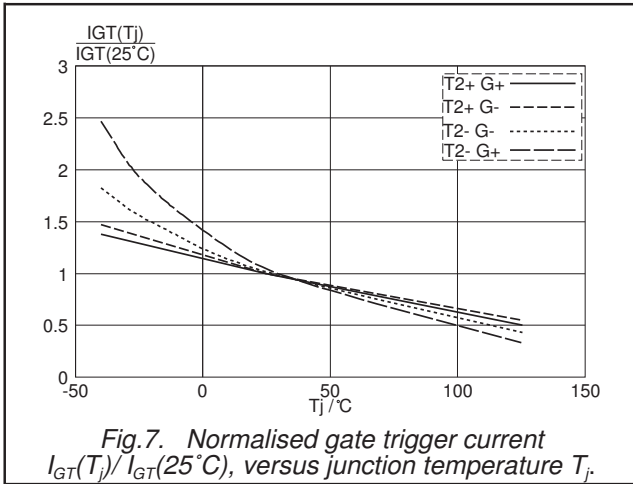


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j) / V_{GT}(25^\circ\text{C})$, versus junction temperature T_j .

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MECHANICAL DATA

Dimensions in mm

Net Mass: 1.4 g

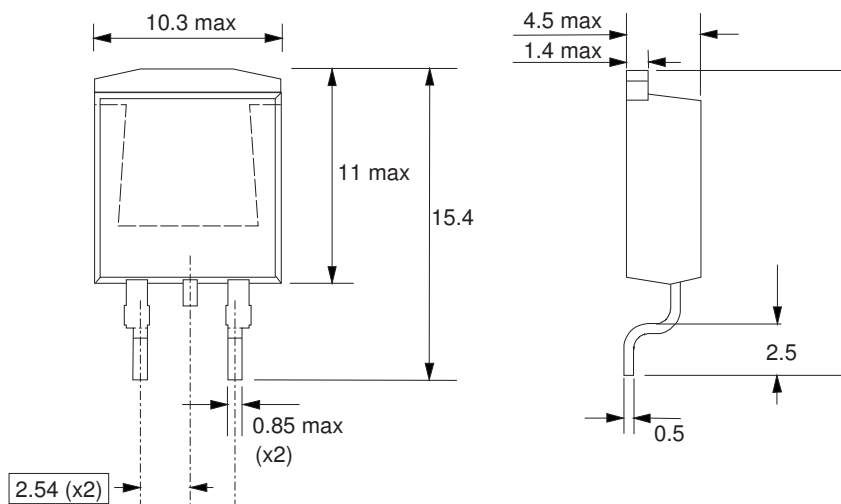


Fig.13. SOT404 : centre pin connected to mounting base.

MOUNTING INSTRUCTIONS

Dimensions in mm

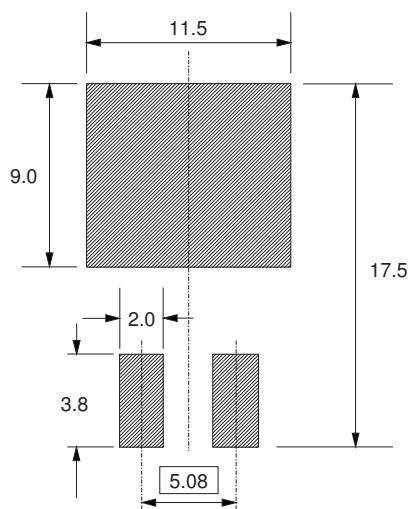


Fig.14. SOT404 : minimum pad sizes for surface mounting.

Notes

- 1. Plastic meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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